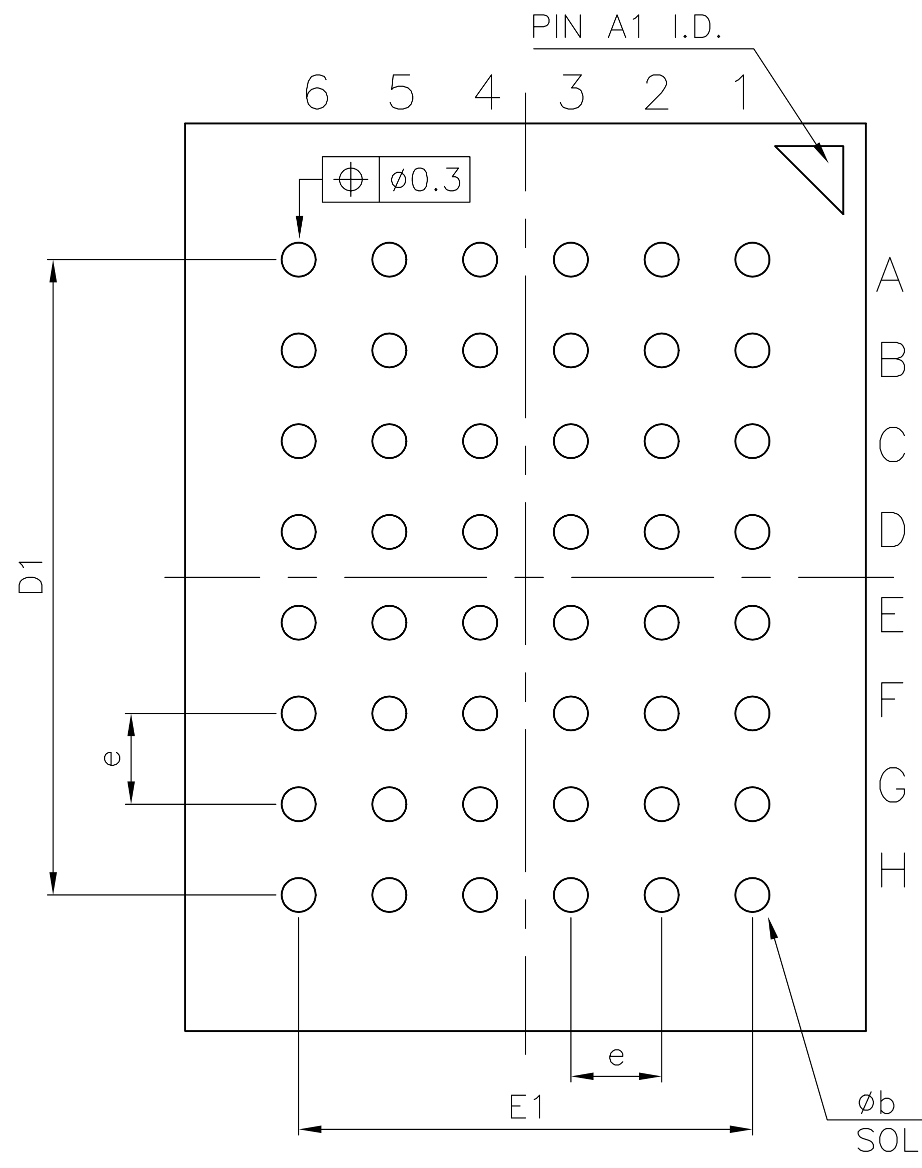
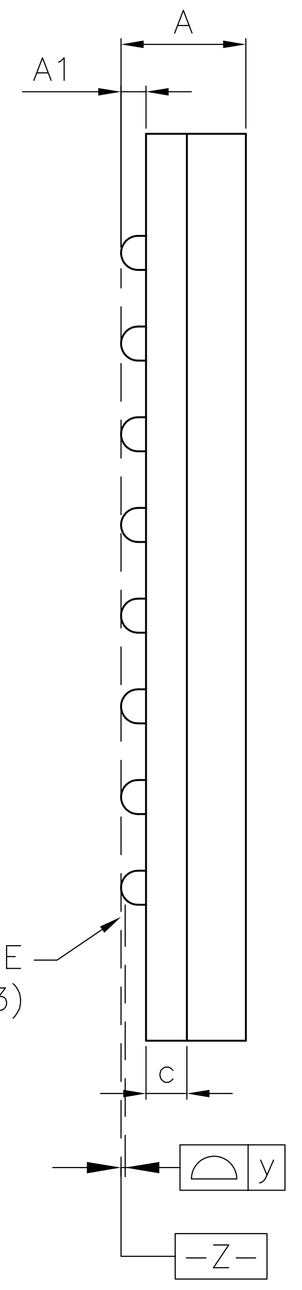
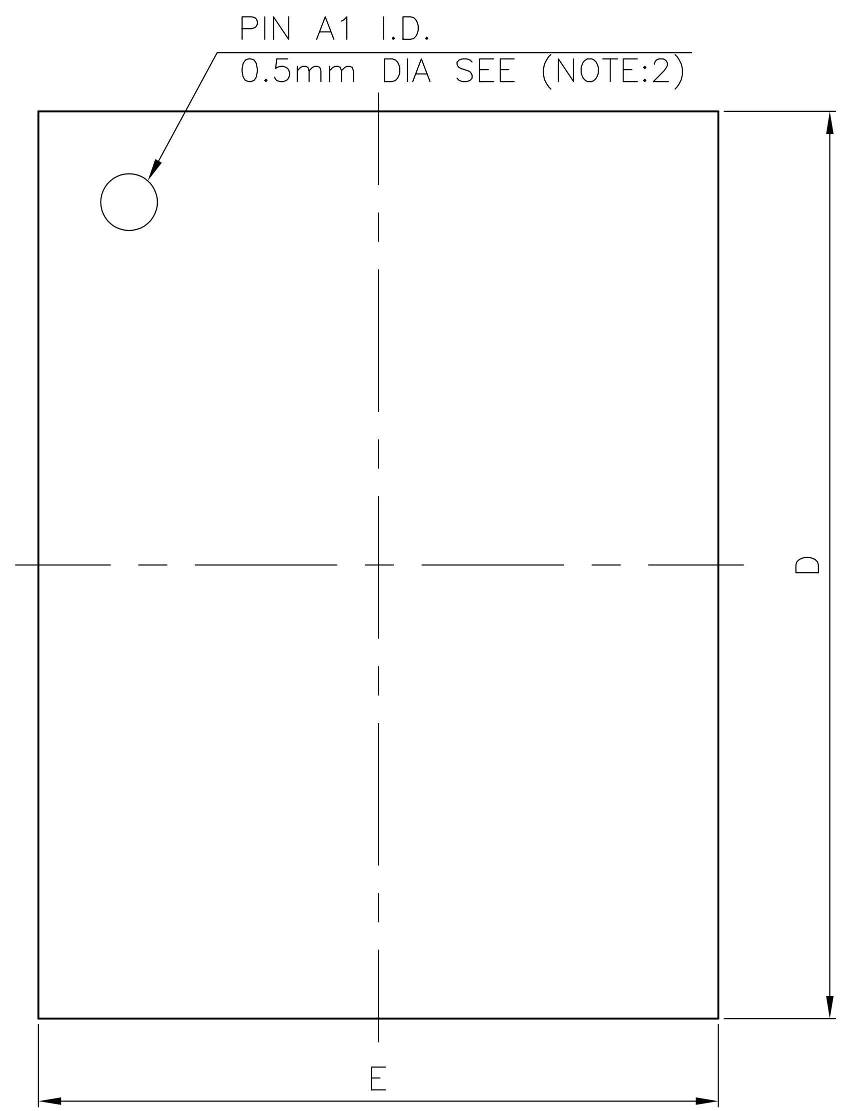


BOTTOM VIEW





TOP VIEW

NOTE :

1. ALL DIMENSION ARE IN MILLIMETERS.
2. PIN A1 ID. TO BE MARKED BY INK OR LASER.
3. PRIMARY DATUM -Z- AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. "e" REPRESENTS THE MAXIMUM SOLDER BALL GRID PITCH.
5. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL PITCH. PARALLEL TO PRIMARY DATUM -Z- .

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.00	1.10	1.20	0.039	0.043	0.047
A1	0.20	0.22	0.25	0.008	0.009	0.010
øb	0.25	0.30	0.40	0.010	0.012	0.016
c	——	0.32	——	——	0.013	——
D	7.90	8.00	8.10	0.311	0.315	0.319
D1	——	5.60	——	——	0.220	——
E	5.90	6.00	6.10	0.232	0.236	0.240
E1	——	4.00	——	——	0.157	——
e	——	0.80	——	——	0.0315	——
y	——	——	0.076	——	——	0.003

CUSTOMER :		LINGSEN PRECISION IND., LTD. 5-1 NAN 2ND ROAD T.E.P.Z TAICHUNG., TAIWAN. R. O. C
APPROVED BY	DATE	TITLE: MINI BGA 48L(6x8mm) PACKAGE OUTLINE DRAWING (Pitch:0.8 mm)
DRAW BY: Vivi Chen	04/19/'01	
CHECK BY: Kevin Liao	04/19/'01	
APPROVAL: Jack Tu	04/20/'01	DWG. NO. PO-MBGA-008 REV. 0
APPROVAL: Jack Tu	04/20/'01	UNIT : mm SCALE : 15/1 SHEET 1 OF 1